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In the Claims

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Please amend Claim 1 as follows.

1 1. **(Currently Amended)** An integrated circuit ~~chip~~
2 board, the ~~chip~~ board comprising:
3 a plurality multiplicity of components semiconductor
4 chips for processing signal groups, wherein a plurality of
5 semiconductor chips exchange signal groups using wireless
6 techniques, the multiplicity of semiconductor chips
7 including; and
8 a group of components for at least one selected
9 semiconductor chip receiving wireless signal groups from at
10 least one predetermined semiconductor chip on the circuit
11 board, the group of components including, selected
12 semiconductor chips having:
13 an antenna for receiving ~~radio frequency~~ wireless
14 signals;
15 a radio frequency wireless signal receiver
16 coupled to the antenna, the receiver detecting the ~~radio~~
17 ~~frequency~~ wireless signals; and
18 a demodulator coupled to the receiver, the
19 demodulator recovering signal groups in the radio frequency
20 wireless signals, the signal groups being applied to the
21 plurality of components.
22
23 2. **(Withdrawn; Non-Elected)**
24

1 Please amend Claim 3 as follows.

2

3 3. **(Currently Amended)** The chip integrated circuit
4 board as recited in claim 1 wherein signals received by the
5 ~~radio frequency~~ the selected semiconductor chip receiver
6 are modulated with a modulation from the group consisting
7 of amplitude modulation and frequency modulation.

8

9 Please amend Claim 4 as follows.

10

11 4. **(Currently Amended)** The chip integrated circuit
12 board as recited in claim 1 wherein the selected
13 semiconductor chip further ~~including~~ includes an analyzer,
14 the analyzer receiving signals signal groups from the
15 demodulator, the analyzer ~~decodes~~ decoding the signal from
16 the demodulator into a plurality of logic signals.

17

18 5. **(Withdrawn; Non-Elected Claim)**

19

20 6. **(Withdrawn; Non-Elected Claim)**

21

22 7. **(Withdrawn; Non-Elected Claim)**

23

24

25 Please amend Claim 8 as follows.

26

27 8. **(Currently Amended)** The chip integrated circuit
28 board as recited in claim 1 wherein the signal groups
29 include a header portion, a data portion, and a tail
30 portion.

1 Please amend Claim 9 as follows.

2

3 9. **(Currently Amended)** A method for transferring
4 logic signal groups between ~~integrated circuit~~ semiconductor
5 chips, the method comprising:

6 modulating and transmitting a ~~radio frequency wireless~~
7 signal by a first ~~integrated circuit~~ semiconductor chip,
8 the wireless signal being modulated with logic signal
9 groups generated by the first ~~integrated circuit~~
10 semiconductor chip; and

11 receiving and demodulating the ~~radio frequency~~
12 wireless signal by the ~~a second integrated circuit~~
13 semiconductor chip.

14

15 Please amend Claim 10 as follows.

16

17 10. **(Currently Amended)** The method as recited in
18 claim 9 wherein the ~~radio frequency wireless~~ signal
19 transmits signal groups formatted in a serial format.

20

21 11. **(Withdrawn; Non-Elected Claim)**

22

23 Please amend Claim 12 as follows.

24

25 12. **(Currently Amended)** The method as recited in
26 claim 9 wherein the ~~modulation of the carrier frequency~~
27 wireless signal transmitting the signal groups is
28 modulation modulated with a modulation selected from the
29 group consisting ~~or~~ of amplitude modulation and frequency
30 modulation.

1 Please amend Claim 13 as follows.

2

3 **13. (Currently Amended)** The method as recited in
4 claim 9 wherein a ~~transmitted wireless~~ signal is encoded
5 ~~with a signal identifying to identify~~ a preselected pattern
6 of signals.

7

8 Please amend Claim 14 as follows.

9

10 **14. (Currently Amended)** The method as recited in
11 claim 13 wherein the receiving and demodulating of the
12 wireless signal provide a decoded signal representing a
13 preselected pattern of logic signals.

14

15 Please amend Claim 15 as follows.

16

17 **15. (Currently Amended)** A system for transferring
18 data signal groups between ~~integrated circuit~~ semiconductor
19 chips: the system comprising:

20 ~~a first integrated circuit chip, the first integrated~~
21 ~~circuit at least one transmitting semiconductor chip~~
22 including:

23 a first processing unit; and

24 a ~~radio~~ wireless transmitting unit coupled to the
25 first processing unit and receiving signal groups there
26 from, the ~~radio~~ wireless transmitting unit transmitting the
27 signal groups from the first processing unit; and

28 ~~a second integrated circuit, the second integrated~~
29 ~~circuit at least one receiving semiconductor chip~~
30 including:

1 a second processing unit, and
2 a ~~radio~~ wireless receiving unit coupled to the
3 second processing unit, the ~~radio~~ wireless receiving unit
4 receiving ~~radio~~ the signal groups from the transmitting
5 unit, the ~~transmitting~~ unit receiving unit applying the
6 signal groups to the second processing unit.

7

8 16. **(Withdrawn; Non-Elected Claim)**

9

10 17. **(Withdrawn; Non-Elected)**

11

12 18. **(Original)** The system as recited in claim 15
13 wherein the transmitting ~~unit~~ semiconductor chip includes a
14 synthesizer and the receiving ~~unit~~ semiconductor chip
15 includes an analyzer for processing ~~serial~~ serially
16 transmitted ~~information~~ signal groups.

17

18 Please amend Claim 19 as follows.

19

20 19. **(Currently Amended)** The system as recited in
21 claim 15 wherein the ~~first integrated circuit~~ transmitting
22 semiconductor chip is located on a first circuit board and
23 the ~~second integrated circuit~~ receiving semiconductor chip
24 is located on a second circuit board, the first circuit
25 board and the second circuit board being in a stacked
26 configuration.

27

28

1 20. **(Original)** The system as recited in claim 15
2 wherein the signal groups include a header portion, a data
3 portion and a tail portion.

4

5 Please add Claim 21.

6

7 21. **(New)** The integrated circuit board as recited
8 in claim 1 wherein the integrated circuit board is a
9 semiconductor substrate, the semiconductor chips being
10 fabricated on the semiconductor substrate.

11

12 Please add Claim 22.

13

14 22. **(New)** The method as recite in claim 9 wherein
15 the semiconductor chips are positioned on an integrated
16 circuit board.

17

18 Please add Claim 23.

19

20 23. **(New)** The system as recited in claim 15
21 wherein the transmitting semiconductor chip and the
22 receiving semiconductor chip are fabricated on the same
23 substrate.